TOSHIBA {DISCRETE/OPTO}

29072906910 兴时的 (DISCRETE/OPTO) 99D 16743 DT-39-13 TOSHIBA FIELD EFFECT TRANSISTOR SEMICONDUCTOR 2 S K 6 9 4 TECHNICAL DATA SILICON N CHANNEL MOS TYPE $(\pi - MOSI)$ INDUSTRIAL APPLICATIONS Unit in mm HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS. CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR 20.5 MAX ø33±02 DRIVE APPLICATIONS. o, 110 FEATURES: 2.50 20 • Low Drain-Source ON Resistance : R_{DS(ON)}=0.40Ω (Typ.) 20.406 . High Forward Transfer Admittance : |Y_{fs}|=9.05 (Typ.) . Low Leakage Current : IGSS=±100nA(Max.) @ VGS=±20V <u>+03</u> 1.0-02 I_{DSS}= 300µA(Max.) @ V_{DS}=500V 545±015 545±015 . Enhancement-Mode : V_{th}=2.0∿4.0V @ V_{DS}=10V,I_D=1mA 20 90 MAXIMUM RATINGS (Ta=25°C) 1. GATE 2. DRAIN (HEAT SINK) CHARACTERISTIC SYMBOL RATING UNIT 3 SOURCE Drain-Source Voltage V_{DSX} 500 ۷ JEDEC Drain-Gate Voltage (R_{GS}=20kΩ) 500 ۷ VDGR EIAJ Gate-Source Voltage V VGSS ±20 TOSHIBA 2-21F1B DC(Tc=25°C) Weight : 9.75g ID 12 Drain Current A Pulse 48 IDP Drain Power Dissipation ₽D 150 W (Tc=25°C) Channel Temperature Tch 150 °C Storage Temperature Range Tstg -55~150 °C THERMAL CHARACTERISTICS CHARACTERISTIC SYMBOL MAX. UNIT 0.83 °C/W Rth(j-c) Thermal Resistance, Junction to Case 30 °C/W R_{th(j-a)} Thermal Resistance, Junction to Ambient Muximum Lead Temperature for Soldering °C TL 300 Purposes (1.6mm from case for 10 seconds)

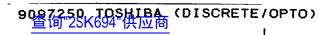
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SEMICONDUCTOR TECHNICAL DATA

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ELECTRICAL	CHARACTERISTICS	(Ta=25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Drain Cut-off Current		IDSS	V _{DS} =500V, V _{GS} =0V	-	-	300	μA
Drain-Source Breakdown Voltage		V(BR)DSS	ID=10mA, VGS=0V	500	-	-	v
Gate Threshold Voltage		V _{th}	V _{DS} =10V, I _D =1mA	2.0	-	4.0	v
Forward Transfer Admittance		Yfs	V _{DS} =10V, I _D =7A	6.0	9.0	-	S
Drain-Source ON Resistance		R _{DS} (ON)	ID=7A , VGS=10V	-	0.40	0.50	ß
Drain-Source ON Voltage		V _{DS(ON)}	ID=12A, VGS=10V	-	5.3	7.0	v
Input Capacitance		Ciss	-	-	2300	3600	
Reverse Transfer Capacitance		Crss	V _{DS} =10V, V _{GS} =0V, f=1MHz	-	450	680	pF
Output Capacitance		Coss		-	1000	1400	
Switching Time	Rise Time	tr		-	70	140	ns
	Turn-on Time	ton		-	100	200	
	Fall Time	tf			75	150	
	Turn-off Time	toff	VIN:tr,tf<5ms V _{DD} ≒210V Duty≤1%	-	350	700	
Total Gate Charge (Gate-Source Pius Gate-Drain)		Qg		-	82	110	
Gate-Source Charge		Qgs	ID=12A , V _{GS} =10V V _{DD} =400V	-	47	-	лС
Gate-Drain ("Miller") Charge		Qgd			35	-	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta=25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	IDR	·	-	-	12	A
Pulse Drain Reverse Current	IDRP		- 1	-	48	A
Diode Forward Voltage	V _{DSF}	I _{DR} =12A , V _{GS} =OV	-	-	1.7	v
Reverse Recovery Time	trr	I _{DR} =12A	-	400	-	ns
Reverse Recovered Charge	Qrr	dI _{DR} /dt=100A/µs	-	4.0		μC

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